L Number	Hits	Search Text	DB	Time stamp
1	2915	wafer adj alignment	USPAT;	2003/06/23
†			US-PGPUB;	12:14
1			EPO; JPO;	
			DERWENT; IBM TDB	:
8	110226	light same measurement	USPAT;	2003/06/23
"	110220	11gii same measaremeiis	US-PGPUB;	12:15
			EPO; JPO;	
			DEPWENT;	
			IBM_TDB	
22	0	mems and ((wafer adj alignment) and	USPAT; US-PGPUB;	2003/06/23
		(light same measurement))	EPO; JPO;	12.13
			DERWENT;	
			IBM TDB	
15	438	(wafer adj alignment) and (light same	USPAT;	2003/06/23
		measurement)	US-PGPUB;	12:16
			EPO; JPO;	
			DERWENT;	
_	16291	dicing	IBM_TDB USPAT;	2003/06/23
1	10291	4101119	US-PGPUB;	12:14
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	49		USPAT;	2003/06/12
		electro adj mechanical)) and dicing	US-PGPUB;	10:58
			EPO; JPO; DERWENT;	
			IBM TDB	
-	299	wafer adj bonding and mems	USPAT;	2003/06/12
			US-PGPUB;	11:09
			EPO; JPO;	
			DEPWENT;	
	46	dicing and (wafer adj bonding and mems)	IBM_TDB USPAT;	2003/06/12
-	40	dicing and (water ad) bonding and mems)	US-PGPUB;	11:11
			EPO; JPO;	11111
			DERWENT;	
			IBM_TDB	, ,
-	3	("6452238").PN.	USPAT;	2003/06/12
			US-PGPUB; EPO; JPO;	11:17
			DERWENT;	
			IBM TDB	
-	5	("4873871"   "6310371"   "6326682"	USPĀT	2003/06/12
		"6180989"   "6369931").PN.		11:16
_	0	6452238.URPN.	USPAT	2003/06/12
	972	   wafer adj orientation	USPAT;	11:17
_	9/2	warer auj Offencacion	US-PGPUB;	11:17
			EPO; JPO;	
			DEPWENT;	
			IBM_TDB	
-	24138	mems	USPAT;	2003/06/23
			US-PGPUB; EPO; JPO;	12:15
			DEPWENT;	
			IBM TDB	
_	7	(wafer adj orientation) and mems	USPAT;	2003/06/12
			US-PGPUB;	11:18
			EPO; JPO;	
			DEPWENT;	
_	327	   wafer adj bonding and (mems or micro adj	IBM_TDB USPAT;	2003/06/12
_	34/	electro adj mechanical)	US-PGPUB;	11:20
			EPO; JPO;	
			DEPWENT;	
			IBM TDB	

_	2475	wafer adj bonding	USPAT; US-PGPUB;	2003/06/12 11:21
			EPO; JPO; DERWENT; IBM TDB	
_	299	mems and (wafer adj bonding)	USPAT; US-PGPUB;	2003/06/12
			EPO; JPO; DERWENT;	
_	259	dicing and (wafer adj bonding)	IBM_TDB USPAT;	2003/06/12
			US-PGPUB; EPO; JPO;	11:21
	4.6		DERWENT; IBM_TDB	2003/06/12
_	46	mems and (dicing and (wafer adj bonding))	USPAT; US-PGPUB; EPO; JPO;	11:23
			DERWENT; IBM TDB	
_	275443	packaging	USPĀT; US-PGPUB;	2003/06/12 11:23
			EPO; JPO; DERWENT;	
_	3187	mems and packaging	IBM_TDB USPAT; US-PGPUB;	2003/06/12
			EPO; JPO; DERWENT;	11.23
_	137	dicing and (mems and packaging)	IBM_TDB USPAT;	2003/06/12
			US-PGPUB; EPO; JPO;	11:23
_	2	("6521477").PN.	DERWENT; IBM_TDB USPAT;	2003/06/12
		( 322177	US-PGPUB; EPO; JPO;	12:08
			DERWENT; IBM_TDB	
_	46	mems and die and second adj wafer	USPĀT; US-PGPUB; EPO; JPO;	2003/06/12 12:27
			DERWENT;	
-	12	mems adj die and holder	USPAT; US-PGPUB;	2003/06/12 12:27
			EPO; JPO; DERWENT;	
_	15	bonding and holder and mems and second adj substrate	IBM_TDB USPAT; US-PGPUB;	2003/06/12 17:18
			EPO; JPO; DERWENT;	
-	76	mems and dicing and aligning	IBM_TDB USPAT;	2003/06/12
			US-PGPUB; EPO; JPO; DEPWENT;	17:18
_	0	cantiliever adj beam and packaging and	IBM_TDB USPAT;	2003/06/14
		holder and dicing	US-PGPUB; EPO; JPO;	05:31
		cantiliover add beam and dising	DEPWENT; IBM_TDB USPAT;	2003/06/14
_	0	cantiliever adj beam and dicing	US-PGPUB; EPO; JPO;	05:31
			DEPWENT; IBM TDB	

-	112	cantilever adj beam and dicing	USPAT;	2003/06/14
			US-PGPUB;	05:38
	}		EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	67	mems adj die	USPAT;	2003/06/14
1			US-PGPUB;	05:38
			EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
_	4	5494698.URPN.	USPAT	2003/06/14
				05:50